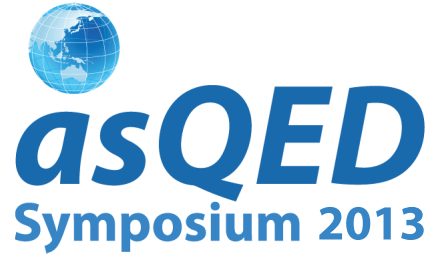


FINAL CALL FOR PAPERS

ASQED 2013

5th Asia Symposium on

QUALITY ELECTRONIC DESIGN


Symposium 2013

Aug. 26-28, 2013 - Penang, Malaysia

www.asqed.com



ASQED 2013 is organized by the International Society for Quality Electronic Design, and is financially sponsored and managed by SHRDC. Symposium gathers leading industrial and educational organizations and it is aimed at bridging the gap among electronic/semiconductor ecosystem members providing electronic design tools and processes, integrated circuit technologies, processes & manufacturing, to achieve design quality. The conference emphasizes innovations and the latest developments in IC and system Design, EDA, Semiconductor Process Technology, IC Packaging, Test, and Manufacturing. ASQED spans two days, in three parallel tracks, hosting over 60 technical presentations, several keynote speakers, tutorials, exhibits and other informal meetings. Past conference proceedings will be published by IEEE and posted in the digital library. ASQED 2013 hosts the 2nd **Microelectronic Olympiad** competition in Malaysia. Refer to the conference website for details.

Papers and tutorial proposals are requested in the following areas

As a premier international conference, ASQED 2013 accepts and promotes papers in following topics:

IC and System-level Design & Test System-level Design, Methodologies & Tools

- Analog, Digital, Mixed-Signal and RFIC Design
- FPGA Architecture, Design, and CAD
- Robust & Power-conscious Circuits & Systems
- Design of Reliable & Fault Tolerant Circuits and Systems
- Design of Embedded Systems

IP Design, Quality, Interoperability and Reuse

- Design Verification and Design for Testability
- Physical Design, Methodologies & Tools
- EDA Methodologies, Tools, Flows

Semiconductor Process and Devices Emerging/Innovative

- Process & Device Technologies
- Yield and Reliability Analysis, Prediction, and Management

Advanced IC Packaging, 3D ICs IC Package - Design Interactions & Co-Design

- Advanced 3D ICs & 3D Packaging
- High density PCB/PWB
- Signal and Power Integrity

Sensors Technology, Design and Applications, MEMS/NEMS

Submission of Papers

Paper submission must be done on-line through the conference web site. The guidelines for the final paper format are provided on the symposium website. Authors should submit FULL-LENGTH, original, unpublished papers (Minimum 4, maximum 10 pages) along with abstract of about 200 words. Please check the as-printed appearance of your paper before sending your paper. In case of any problems, email asqed2013@asqed.com. Please note the following important dates:



Paper Submission Deadline
Acceptance Notifications
Final Camera-Ready paper

May 17, 2013
June 14, 2013
July 19, 2013

Extended

